

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5990878

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	KENICHIRO HATAKEYAMA	02/27/2020
RECEIVING PARTY DATA		
Name:	TEIKOKU CO., LTD.	
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16643640	
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NAME OF SUBMITTER:	NICHOLAS MESITI	
SIGNATURE:	/Nicholas Mesiti/	
DATE SIGNED:	03/02/2020	
	This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3		
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ASSIGNMENT AND DECLARATION

WHEREAS, I,

Kenichiro HATAKEYAMA, a citizen of Japan, with an address at c/o Teikoku Co., Ltd., 1-16, Minoo 6-chome, Minoo-shi Osaka 5620001 Japan,

have invented certain new and useful improvements in

TOPICAL DERMATOLOGICAL COMPOSITION

which is the subject of the U.S. Patent Application No.: 16/643,640, filed March 2, 2020, which claims priority to International Application No.: PCT/JP2018/031635 filed on August 28, 2018, which claims priority to Japanese Patent Application No.: 2017-169233 filed on September 4, 2017, and

WHEREAS, **TEIKOKU CO., LTD.**, having offices at 1-16, Minoo 6-chome, Minoo-shi Osaka 5620001 Japan, is desirous of obtaining the entire right, title and interest in, to and under said improvements and said application; and

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which I hereby acknowledge, I, **Kenichiro HATAKEYAMA**, do hereby assign, transfer and set over to **TEIKOKU CO., LTD.**, its successors, legal representatives and assigns, the entire right title and interest in, to and under said improvements, the above-identified application - including the right to claim priority to said application, all divisions, renewals and continuations thereof, and all Letters Patent which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to

TEIKOKU CO., LTD., its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant and agree that I will communicate to **TEIKOKU CO., LTD.**, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid **TEIKOKU CO., LTD.**, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries;

AND I HEREBY grant Heslin Rothenberg Farley & Mesiti P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document;

AND I HEREBY, as the above-named inventor, declare that the above-identified application was made or authorized to be made by me;

AND I HEREBY, as the above-named inventor, declare that I believe that I am the original inventor of a claimed invention in the above-identified application;

AND I HEREBY state that I have reviewed and understand the contents of the above-identified specification, including the claims;

AND I HEREBY acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56;

AND I HEREBY declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that any willful false statements and the like so

made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 27th day of February, 2020.

Kenichiro Hatakeyama
Kenichiro HATAKEYAMA

Witnessed by: Shinnosuke Hatakeyama Date: 27. FEB. 2020
Signature

Witnessed by: _____ Date: _____
Signature